

## Akros Silicon

Package: 64L QLMP  
 Device: AS1824

MATERIAL	WEIGHT (mg)	Components	CAS Number	Composition %	Weight/Device (mg)	% wt	ppm
Adhesive Sumitomo CRM1076NS	2.3217	Silver	7440-22-4	80.00	1.857360	0.86440	8644
		Epoxy Resins	9003-36-5	10.00	0.232170	0.10805	1080
		Diluent	26447-14-3	6.00	0.139302	0.06483	648
		Dicyandiamide	461-58-5	0.50	0.011609	0.00540	54
		Hardner	620-92-8	3.50	0.081260	0.03782	378
Lead Frame QPL	87.2098	Copper	7440-50-8	97.09	84.667634	39.40352	394035
		Iron	7439-89-6	2.30	2.005825	0.93349	9335
		Lead	7439-92-1	0.01	0.004360	0.00203	20
		Silver	7440-22-4	0.40	0.348839	0.16235	1623
		Phosporous	7723-14-0	0.09	0.078489	0.03653	365
		Zinc	7440-66-6	0.12	0.104652	0.04870	487
Plating 100% matt tin	9.8471	Tin	07440-31-5	99.99	9.846115	4.58229	45823
		Lead	07439-92-1	0.005	0.000492	0.00023	2
		Copper	07440-50-8	0.003	0.000295	0.00014	1
		Antimony	07440-36-0	0.001	0.000098	0.00005	0
Gold wire	2.5617	Gold	7440-57-5	100.00	2.561700	1.19219	11922
Encapsulation Sumitomo G770HCD	105.4298	Silica Fused	60676-86-0	89.70	94.570531	44.01223	440122
		Epoxy Resin	Trade secret	5.00	5.271490	2.45330	24533
		Phenol Resin	Trade secret	5.00	5.271490	2.45330	24533
		Carbon Black	1333-86-4	0.30	0.316289	0.14720	1472
Silicon Chip	7.5032	Si (Die )	7440-21-3	100.00	7.503200	3.49192	34919
Total weight (mg)	214.8733					100.00	1000000